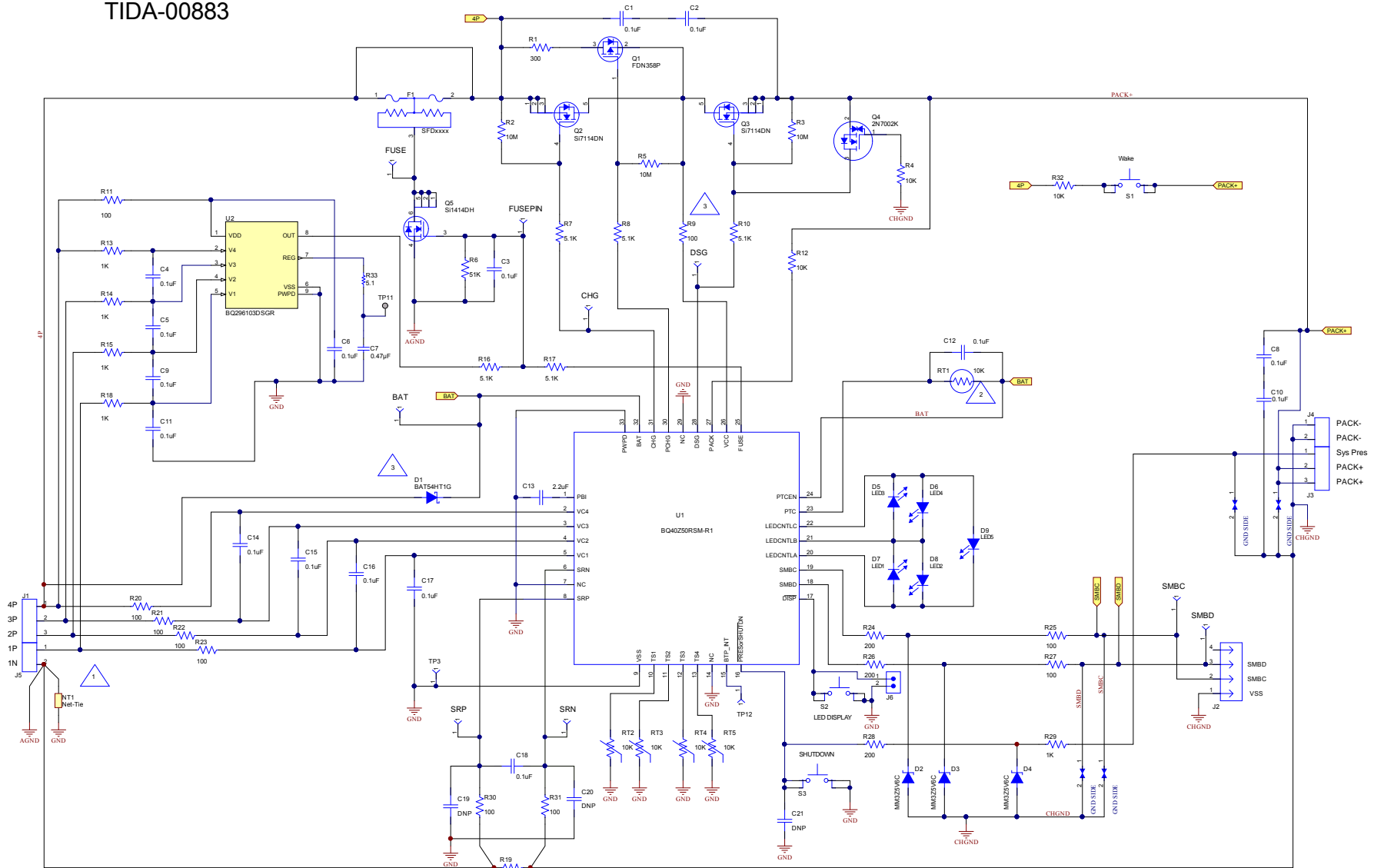


# TIDA-00883



- 1 IC ground should be connected to the 1N cell tab.
- 2 Place RT1 close to Q2 and Q3.
- 3 Replace D1 and R9 with a 10 ohm resistor for single cell applications

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